

Epoxy Woven Aramid



45NK is a woven Kevlar® aramid fiber reinforced multifunctional epoxy laminate and prepreg system engineered to provide in-plane CTE values as low as 6 ppm/°C for compatibility with leadless alumina ceramic chip carriers (LCCC's) and other low expansion SMT devices where control of laminate expansion is critical for solder joint reliability.

Features:

- Meets IPC4101/50 (Type AFG) description and specification
- High Tg (170°C) for improved reliability through process and in-use
- Low Dielectric Constant 3.9
- High modulus (19 x 106 psi) p-aramid woven fiber reinforcement with CTE of -4 ppm/°C provides low X-Y CTE of 5-7 ppm/°C
- Process compatible with conventional high Tg multifunctional epoxy systems
- 100% Organic resin/reinforcement system is suitable for laser drilling
- RoHS/WEEE compliant
- UL-94 V-0

Typical Applications:

- SMT Board Designs using LCCC's or other low expansion chip carriers
- SMT Designs requiring both low in-plane CTE and laser drilling



Typical Properties:

Property	Units	Value	Test Method
Electrical Properties			
Dielectric Constant @ 1 MHz	-	3.9	IPC TM-650 2.5.5.3
@ 1 GHz	-		IPC TM-650 2.5.5.9
Dissipation Factor @ 1 MHz		0.016	IPC TM-650 2.5.5.3
@ 1 GHz			IPC TM-650 2.5.5.9
Volume Resistivity		_	
C96/35/90	MΩ-cm	1.3 x 10 ⁷	IPC TM-650 2.5.17.1
E24/125	MΩ-cm		IPC TM-650 2.5.17.1
Surface Resistivity		7	
C96/35/90	ΜΩ	3.2 x 10 ⁷	IPC TM-650 2.5.17.1
E24/125	ΜΩ		IPC TM-650 2.5.17.1
Electrical Strength	Volts/mil (kV/mm)	750 min	IPC TM-650 2.5.6.2
Dielectric Breakdown	kV		IPC TM-650 2.5.6
Arc Resistance	sec		IPC TM-650 2.5.1
Thermal Properties			
Glass Transition Temperature (Tg)			
TMA	°C		IPC TM-650 2.4.24C
DSC	°C	170	IPC TM-650 2.4.25D
Decomposition Temperature			
Initial	°C		IPC TM-650 2.4.24.6
5% weight loss	°C		IPC TM-650 2.4.24.6
T260	min		IPC TM-650 2.4.24.1
T288	min		IPC TM-650 2.4.24.1
T300	min		IPC TM-650 2.4.24.1
CTE (X,Y)	ppm/°C	5-7	IPC TM-650 2.4.41
CTE (Z)			
< Tg	ppm/°C	75	IPC TM-650 2.4.24C
> Tg	ppm/°C	225	IPC TM-650 2.4.24C
z-axis Expansion (50-260°C)	%	2.8	IPC TM-650 2.4.24C
Mechanical Properties			
Peel Strength to Copper (1 oz/35 micron)			
After Thermal Stress	lb./in (N/mm)	6.0 (1.05)	IPC TM-650 2.4.8C
At Elevated Temperatures	lb./in (N/mm)	6.0 (1.05)	IPC TM-650 2.4.8.2A
After Process Solutions	lb./in (N/mm)	6.0 (1.05)	IPC TM-650 2.4.8C
Young's Modulus CD/MD	Mpsi (GPa)	4.0 (27.5)	ASTM E111
Tensile Strength CD/MD	kpsi (MPa)		ASTM D3039
Poisson's Ratio	-	0.2	ASTM E13204
Physical Properties			
Water Absorption (0.062")	%	0.8	IPC TM-650 2.6.2.1A
Density	g/cm ³	1.37	ASTM D792 Method A
Thermal Conductivity	W/mK	0.22	ASTM E1461
Flammability	class	V0	UL-94

Results listed above are typical properties, provided without warranty, expressed or implied, and without liability. Properties may vary, depending on design and application.

Arion reserves the right to change or update these values.



Availability:

Arlon Part Number	Glass Style	Resin (%)	Volatiles	Nominal Pressed
45NK257	3500 Kevlar	57 ± 3	0.5% max	0.004"
45NK262	3500 Kevlar	62 ± 3	0.5% max	0.0045"

Recommended Process Conditions:

Process inner-layers through develop, etch, and strip using standard industry practices. Use brown oxide on inner layers. Adjust dwell time in the oxide bath to ensure uniform coating.

Bake inner layers in a rack for 60 minutes at 225°F - 250°F (107°C - 121°C) immediately prior to lay-up. Vacuum desiccate the prepreg for 8 – 12 hours prior to lamination.

Lamination Cycle:

- 1) Pre-vacuum for 30 minutes
- 2) Control the heat rise to 8°F-12°F (4.5°C 6.5°C) per minute between 210°F and 300°F (100°C and 150°C)

Panel Size		Pressure		
in.	mm	psi	kg/cm2	
12 x 18	305 x 457	275	19	
16 x 18	406 x 457	350	25	
18 x 24	457 x 610	400	27	

- 3) Product temperature at start of cure = 360°F (180°C).
- 4) Cure time at temperature = 90 minutes
- 5) Cool down under pressure at ≤ 10°F/min (5°C/min)

Process Notes:

Kevlar® fabric compresses and distorts under pressure, more so than E Glass, which dictates the use of lower lamination pressures. The use of an autoclave or vacuum assist lamination makes the use of lower pressure possible. Typically the pressures used under vacuum should be about 50% of those used for standard press lamination e.g. 12" x 18" (30 cm x 46 cm) panel non-vacuum 300 PSI (2 kg /cm2) versus vacuum 150 PSI (10.5 kg/cm2).



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For samples, technical assistance and customer service, please contact Arlon Electronic Materials at the following locations:

NORTH AMERICA:

Arlon EMD, 9433 Hyssop Drive, Rancho Cucamonga, CA Tel: (909) 987-9533 • Fax: (909) 987-8541

FRANCE:

CCI Eurolam 9, rue Marcelin Bertholet 92160 Antony, France

Phone: (33) 146744747 Fax: (33) 146666313

GERMANY:

CCI Eurolam Otto-Hahn-Str. 46 63303 Dreiech Germany

Phone: (49) 610339920 Fax: (49) 6103399229

UK & SCANDINAVIA:

CCI Eurolam – UK Ulness Walton Lane Leyland, PR26 8NB, UK

Phone: (44) 1772452236 Fax: (44) 1772456859

ISRAEL:

Tech Knowledge, Ltd. 159 Yigal Alon Street,

Tel Aviv 6744367, Israel

Phone: (972) 36958117 Fax: (972) 36917117

ITALY:

Dralmi,SAS XãæÓÔ^||ðjãÁ ÁWWWWWWA 20129 Milano Italy

Phone: (39) 025460507 Fax: (39) 0255013199

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SINGAPORE:

C.T.S. Industries Pte Ltd 47 Kaki Bukit Place Singapore 416225

Phone: (65) 6276 3328 Fax: (65) 6276 3336

JAPAN:

Nakao Corp. 12-8 Nihonbashi Hisamatsu-Cho Tokyo 103-0005 Japan

Phone: (81) 336623201 Fax: (81) 336617118

KOREA

UniMicrotek Co. Ltd. 478 Baekbeom-Ro, Bupyeong-Gu Incheon, Korea

Phone: (82) 32-424-1776 Fax: (82) 505-720-1785

CHINA:

Zack Peng Room 6A, Unit 2, Bldg 2 Jin Cheng Shi Dai, Tian Road Shenzhen, China 518103

Phone: (86) 75528236491 Fax: (86) 75528236463

INDIA:

Synertec 301 Raheja Chambers,12 Museum Rd Bangalore, India 560001

Phone: (91) 80-25585432 Fax: (91) 80-25588565